### T-1 3/4 (5mm) RIGHT ANGLE LED INDICATOR

Part Number: L-1503CB/1SRD

Super Bright Red

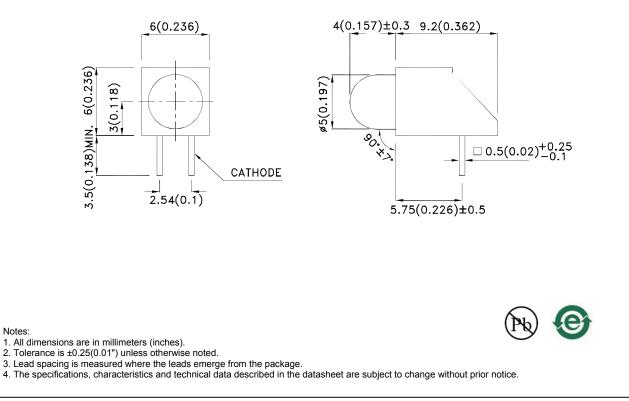
#### Features

- Low power consumption.
- Versatile mounting on P.C. board or panel.
- T-1 3/4 diameter flangeless package.
- Reliable and rugged.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

#### **Package Dimensions**



SPEC NO: DSAC7366 APPROVED: WYNEC REV NO: V.10A CHECKED: Allen Liu DATE: JAN/16/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102000624

### Selection Guide

Part No.		lv (mcd) [2] @ 20mA		Viewing Angle [1]	
			Min.	Тур.	201/2
L-1503CB/1SRD	Super Bright Red (GaAlAs)	Red Diffused	500	1000	60°
			*120	*260	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
\*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ. Max		Units	Test Conditions	
λpeak	Peak Wavelength	Super Bright Red	655		nm	IF=20mA	
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA	
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA	
lr	Reverse Current	Super Bright Red		10	uA	VR = 5V	

Notes:

Wavelength: +/-1nm.
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

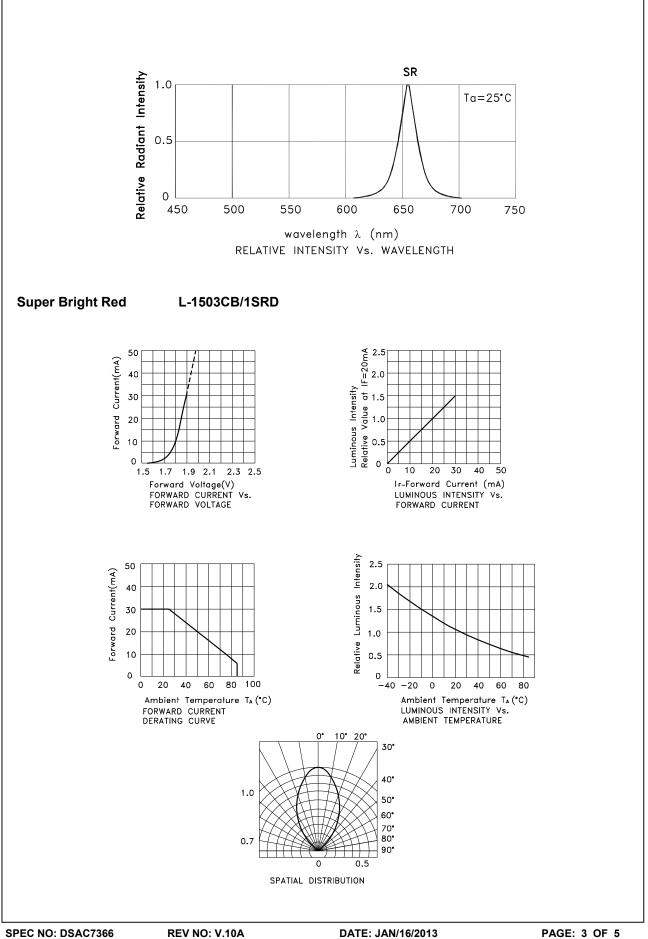
### Absolute Maximum Ratings at TA=25°C

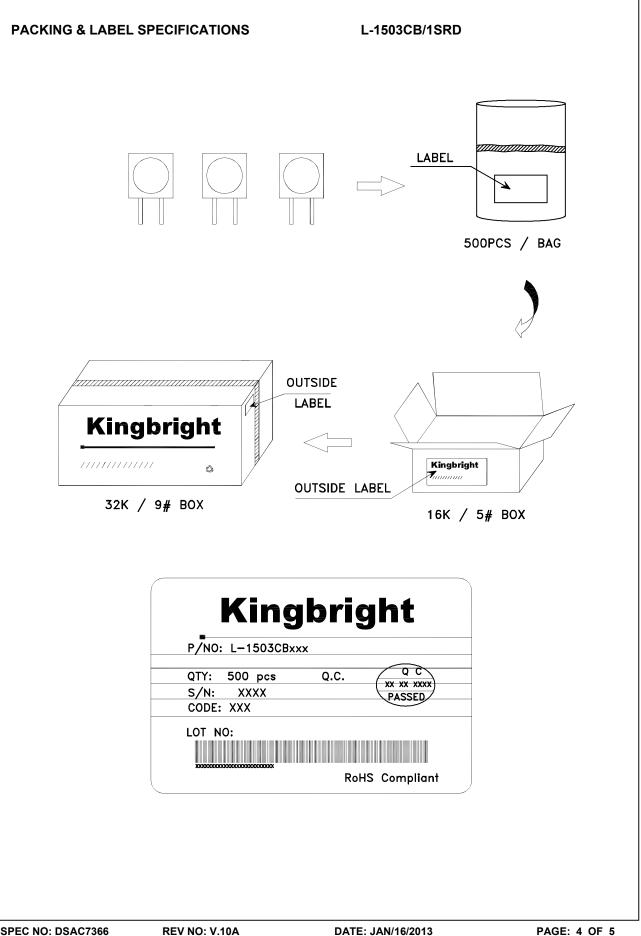
Super Bright Red		
75	mW	
30	mA	
155	mA	
5	V	
-40°C To +85°C		
260°C For 3 Seconds		
260°C For 5 Seconds		
	75 30 155 5 -40°C To +85°C 260°C For 3 Seconds	

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

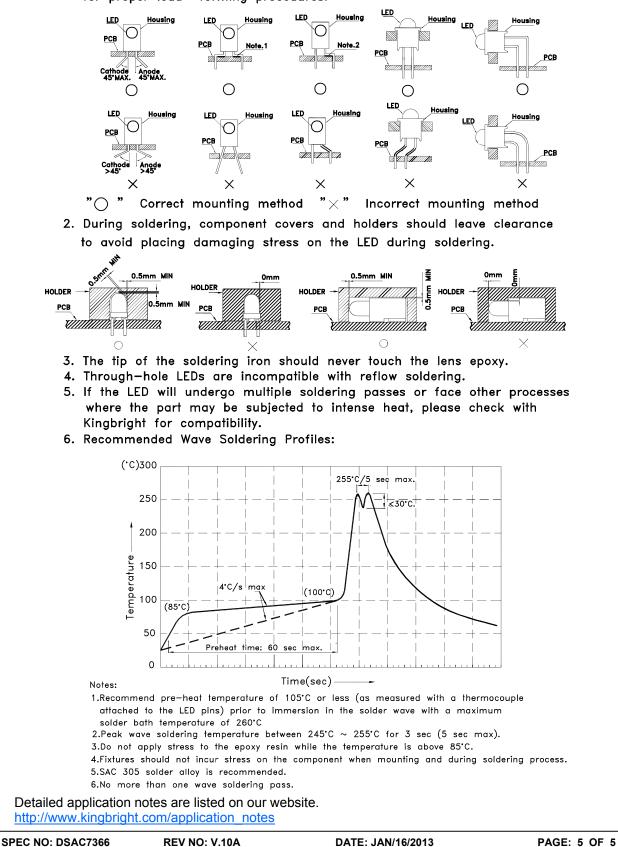
2. 2mm below package base.
3. 5mm below package base.





### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



REV NO: V.10A CHECKED: Allen Liu DATE: JAN/16/2013 DRAWN: F.Cui PAGE: 5 OF 5 ERP: 1102000624